Product Change Notification

Change Notification #:	**117718 - 00**
Change Title:	**Select Intel® SSD 665p Series, PCN 117718-00, Product Discontinuance, End of Life**
Date of Publication:	**August 3, 2020**

Key Characteristics of the Change:

Product Discontinuance

Forecasted Key Milestones:

Last Product Discontinuance Order Date:	January 31, 2021
Last Product Discontinuance Shipment Date:	April 30, 2021

Description of Change to the Customer:

Intel is announcing the End of Life timeline for the Intel® SSD 665p Series.

The Intel® SSD 665p Series products listed on the "Products Affected/Intel Ordering Codes" table below will be discontinued and unavailable for additional orders after the "Last Product Discontinuance Order Date."

Effective "Last Ship Date" Intel will stop shipping Intel® SSD 665p Series hardware.

Customer Impact of Change and Recommended Action:

Please determine your remaining demand for the products listed in the "Products Affected/Intel Ordering Codes" table and place your "Last Product Discontinuance Order" in accordance with the "Key Milestones" listed above.

Intel will make commercially reasonable efforts to support last time order quantities.

Please contact your local Intel Field Sales representative if you have any further questions about this End of Life notice.

Products Affected / Intel Ordering Codes:

Product Name	Product Code	MM#
Intel® SSD 665p Series (512GB, M.2 80mm PCIe 3.0 x4, 3D3, QLC) Generic Single Pack	SSDPEKNW512G901	999GPA
Intel® SSD 665p Series (1.0TB, M.2 80mm PCIe 3.0 x4, 3D3, QLC) Generic Single Pack	SSDPEKNW010T901	999GPC
Intel® SSD 665p Series (2.0TB, M.2 80mm PCIe 3.0 x4, 3D3, QLC) Generic Single Pack	SSDPEKNW020T901	999GPD
Intel® SSD 665p Series (512GB, M.2 80mm PCIe 3.0 x4, 3D3, QLC) Generic 100 Pack	SSDPEKNW512G9	999GPZ
Intel® SSD 665p Series (1.0TB, M.2 80mm PCIe 3.0 x4, 3D3, QLC) Generic 100 Pack	SSDPEKNW010T9	999GR0
Intel® SSD 665p Series (2.0TB, M.2 80mm PCIe 3.0 x4, 3D3, QLC) Generic 100 Pack	SSDPEKNW020T9	999GR1
ntel® SSD 665p Series (1.0TB, M.2 80mm PCIe 3.0 x4, 3D3, QLC) Retail Box Single Pack	SSDPEKNW010T9X1	999HHA
Intel® SSD 665p Series (2.0TB, M.2 80mm PCIe 3.0 x4, 3D3, QLC) Retail Box Single Pack	SSDPEKNW020T9X1	999HHG

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
August 3, 2020	00	Originally Published PCN

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com
Asia Pacific/PRC Contact: apacgccb@intel.com
Europe Email: eccb@intel.com
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